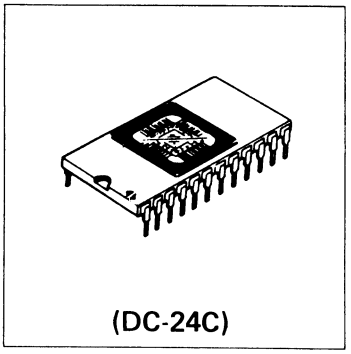
HN462732

4096-word × 8-bit UV Erasable and Programmable Read Only Memory

The HN462732 is a 4096 word by 8 bit erasable and electrically programmable ROM. This device is packaged in a 24-pin, dual-in-line package with transparent lid. The transparent lid allows the user to expose the chip to ultraviolet light to erase the bit pattern, whereby a new pattern can then be written into the device.

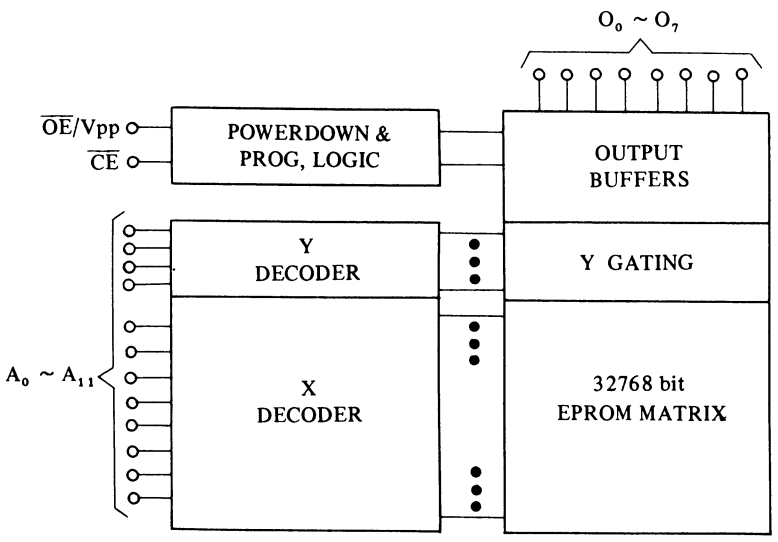


(DC-24C)

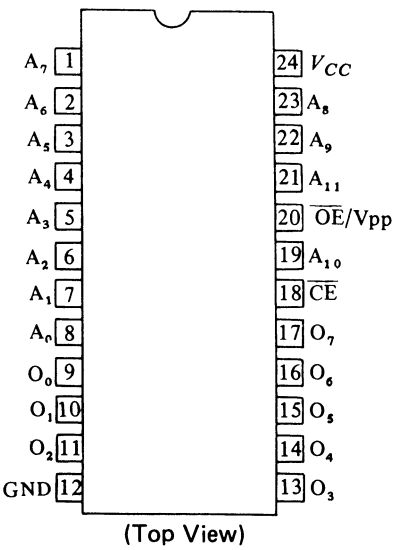
■ FEATURES

- Single Power Supply . . . . . +5V ±5%
- Simple Programming . . . . . Program Voltage: +25V D.C.
  Program with One 50ms Pulse
- Static . . . . . No Clocks Required
- Inputs and Outputs TTL Compatible During Both Read and Program Modes
- Fully Decoded On-Chip Address Decode
- Access Time . . . . . 450ns Max.
- Low Power Dissipation . . . . . 150mA Max. Active Current
  30mA Max. Standby Current
- Three State Output . . . . . OR-Tie-Capability
- Compatible with INTEL 2732

■ BLOCK DIAGRAM



■ PIN ARRANGEMENT



(Top View)

■ MODE SELECTION

Mode \ Pins	$\overline{CE}$ (18)	$\overline{OE}/V_{PP}$ (20)	V_{CC} (24)	Outputs (9 ~ 11, 13 ~ 17)
Read	V_{IL}	V_{IL}	+5	Dout
Stand by	V_{IH}	Don't Care	+5	High Z
Program	V_{IL}	V_{PP}	+5	Din
Program Verify	V_{IL}	V_{IL}	+5	Dout
Program Inhibit	V_{IH}	V_{PP}	+5	High Z

■ ABSOLUTE MAXIMUM RATINGS

Item	Symbol	Value	Unit
Operating Temperature Range	T_{opr}	0 to + 70	°C
Storage Temperature Range	T_{stg}	−65 to + 125	°C
All Input and Output Voltages*	V_{IN}, V_{out}	−0.3 to + 7	V
V_{PP} Voltage*	$\overline{OE}/V_{PP}$	−0.3 to +28	V

*with respect to GND

■ READ OPERATION

• D. C. AND OPERATING CHARACTERISTICS (T_a=0 to +70°C, V_{CC}=5V±5%)

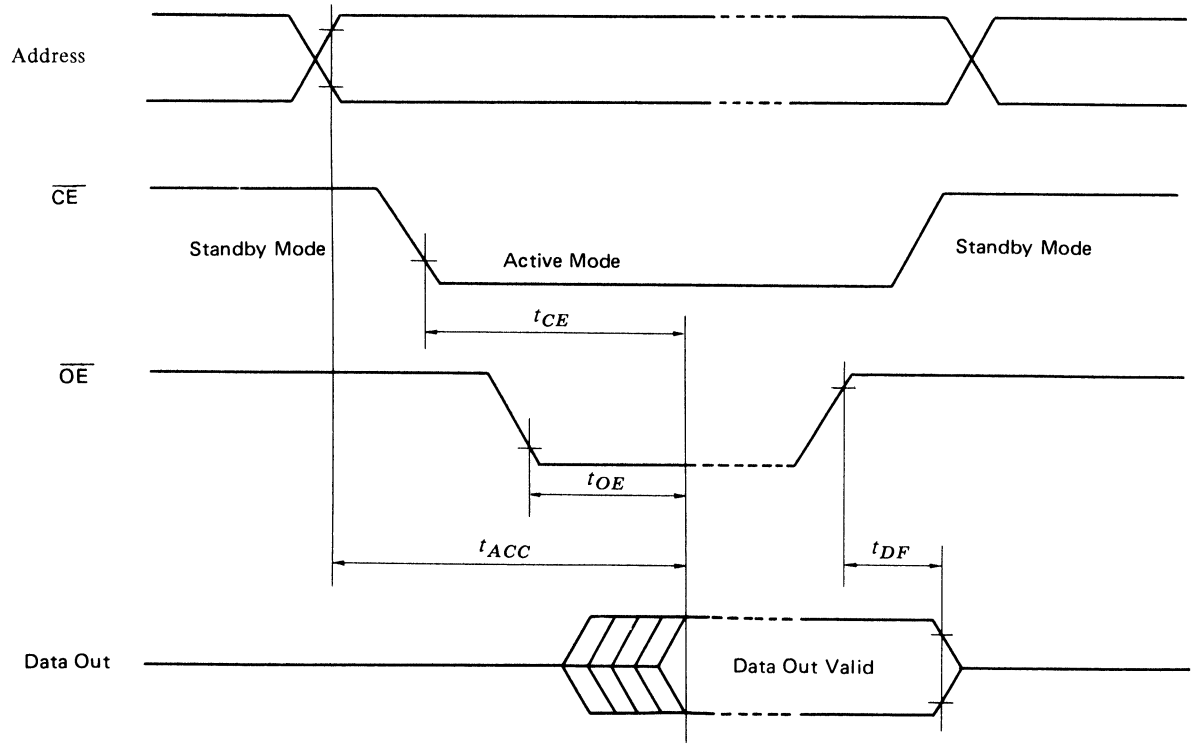
Parameter	Symbol	Test Conditions	min.	typ.	max.	Unit
Input Leakage Current (Except $\overline{OE}/V_{PP}$)	I_{LI1}	V_{IN} = 5.25 V	–	–	10	μA
$\overline{OE}/V_{PP}$ Input Leakage Current	I_{LI2}	V_{IN} = 5.25 V	–	–	300	μA
Output Leakage Current	I_{LO}	V_{out} = 5.25 V	–	–	10	μA
V_{CC} Current (Standby)	I_{CC1}	$\overline{CE}$ = V_{IH}, $\overline{OE}$ = V_{IL}	–	–	30	mA
V_{CC} Current (Active)	I_{CC2}	$\overline{OE}$ = $\overline{CE}$ = V_{IL}	–	–	150	mA
Input Low Voltage	V_{IL}		−0.1	–	0.8	V
Input High Voltage	V_{IH}		2.0	–	V_{CC} + 1	V
Output Low Voltage	V_{OL}	I_{OL} = 2.1 mA	–	–	0.45	V
Output High Voltage	V_{OH}	I_{OH} = −400 μA	2.4	–	–	V

• A. C. CHARACTERISTICS (T_a=0 to +70°C, V_{CC}=5V±5%)

Parameter	Symbol	Test Conditions	min.	typ.	max.	Unit
Address to Output Delay	t_{ACC}	$\overline{CE}$ = $\overline{OE}$ = V_{IL}	–	–	450	ns
$\overline{CE}$ to Output Delay	t_{CE}	$\overline{OE}$ = V_{IL}	–	–	450	ns
Output Enable to Output Delay	t_{OE}	$\overline{CE}$ = V_{IL}	–	–	120	ns
Output Enable High to Output Float	t_{DF}	$\overline{CE}$ = V_{IL}	0	–	100	ns
Address to Output Hold	t_{OH}	$\overline{CE}$ = $\overline{OE}$ = V_{IL}	0	–	–	ns

• SWITCHING CHARACTERISTICS

Test Condition
Input Pulse Levels: 0.8V to 2.2V
Input Rise and Fall Times: ≤20ns
Output Load: 1TTL Gate + 100pF
Reference Level for Measuring Timing: Inputs 1V and 2V
Outputs 0.8V and 2V



• CAPACITANCE (T_a=25°C, f=1 MHz)

Parameter	Symbol	Test Conditions	min.	typ.	max.	Unit
Input Capacitance (Except $\overline{OE}/V_{PP}$)	C_{IN1}	V_{IN} = 0 V	–	–	6	pF
$\overline{OE}/V_{PP}$ Input Capacitance	C_{IN2}	V_{IN} = 0 V	–	–	20	pF
Output Capacitance	C_{out}	V_{out} = 0 V	–	–	12	pF

■ PROGRAMMING OPERATION

• D.C. PROGRAMMING CHARACTERISTICS (V_{CC}=5V±5%, V_{pp}=25V±1V, T_a=25°C±5°C)

Parameter	Symbol	Test Conditions	min.	typ.	max.	Unit
Input Leakage Current	I_{LI}	V_{IN} = 5.25/0.4 V	–	–	10	μA
Output Low Voltage During Verify	V_{OL}	I_{OL} = 2.1 mA	–	–	0.4	V
Output High Voltage During Verify	V_{OH}	I_{OH} = −400 μA	2.4	–	–	V
V_{CC} Supply Current	I_{CC}		–	–	150	mA
Input Low Level	V_{IL}		−0.1	–	0.8	V
Input High Level (All Inputs Except $\overline{OE}/V_{PP}$)	V_{IH}		2.0	–	V_{CC} + 1	V
V_{PP} Supply Current	I_{PP}	$\overline{CE}$ = V_{IL}, $\overline{OE}$ = V_{PP}	–	–	30	mA

• A.C. PROGRAMMING CHARACTERISTICS (V_{CC}=5V±5%, V_{pp}=25V±1V, T_a=25°C±5°C)

Parameter	Symbol	Test Conditions	min.	typ.	max.	Unit
Address Setup Time	t_{AS}		2	–	–	μs
$\overline{OE}$ Setup Time	t_{OES}		2	–	–	μs
Data Setup Time	t_{DS}		2	–	–	μs
Address Hold Time	t_{AH}		0	–	–	μs
$\overline{OE}$ Hold Time	t_{OEH}		2	–	–	μs
Data Hold Time	t_{DH}		2	–	–	μs
Chip Enable to Output Float Delay	t_{DF}		0	–	120	ns
Data Valid from $\overline{CE}$	t_{DV}	$\overline{CE}$ = V_{IL}, $\overline{OE}$ = V_{IL}	–	–	1	μs
$\overline{CE}$ Pulse Width During Programming	t_{PW}		45	50	55	ms
$\overline{OE}$ Pulse Rise Time During Programming	t_{PRT}		50	–	–	ns
V_{PP} Recovery Time	t_{VR}		2	–	–	μs

• SWITCHING CHARACTERISTICS

Test Conditions

Input Pulse Level: 0.8V to 2.2V

Input Rise and Fall Times: ≤20ns

Output Load: 1 TTL Gate + 100pF

Reference Level for Measuring Timing: Inputs; 1V and 2V,
Outputs; 0.8V and 2V